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(12) **United States Design Patent**  
**Frank et al.**

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(54) **MODULE**

(71) Applicant: **SEMIKRON ELEKTRONIK GMBH & CO. KG**, Nuremberg (DE)

(72) Inventors: **Thomas Frank**, Lauf (DE); **Stefan Weiss**, Höchstadt (DE); **Patrick Sturm**, Nuremberg (DE); **Thomas Ziegler**, Piech (DE)

(73) Assignee: **SEMIKRON ELEKTRONIK GmbH & CO. KG**, Nuremberg (DE)

(\*\*) Term: **15 Years**

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(51) **LOC (13) Cl.** ..... **15-01**

(52) **U.S. Cl.**  
USPC ..... **D15/5**; D13/110; D13/162

(58) **Field of Classification Search**  
USPC ..... D15/1-9; D14/299, 358, 434; D13/49, D13/50, 60, 103, 107, 110, 117, 118, 124, D13/125, 126-127, 146, 152, 182, 184, D13/162

CPC ..... H02J 7/003; H02J 7/0042; H01L 23/02; H01L 23/04; H01L 23/053; H01L 23/12; H02M 1/00; H02M 1/003; H05K 5/00; H05K 5/026; H05K 5/0243; B60L 1/00; B60L 1/002; B60L 15/34; B60L 15/38; B60L 53/20; B60L 53/22

See application file for complete search history.

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*Primary Examiner* — Sheryl Lane

*Assistant Examiner* — Mark T. Philipps

(74) *Attorney, Agent, or Firm* — Andrew F. Young, Esq.; Nolte Lackenbach Siegel

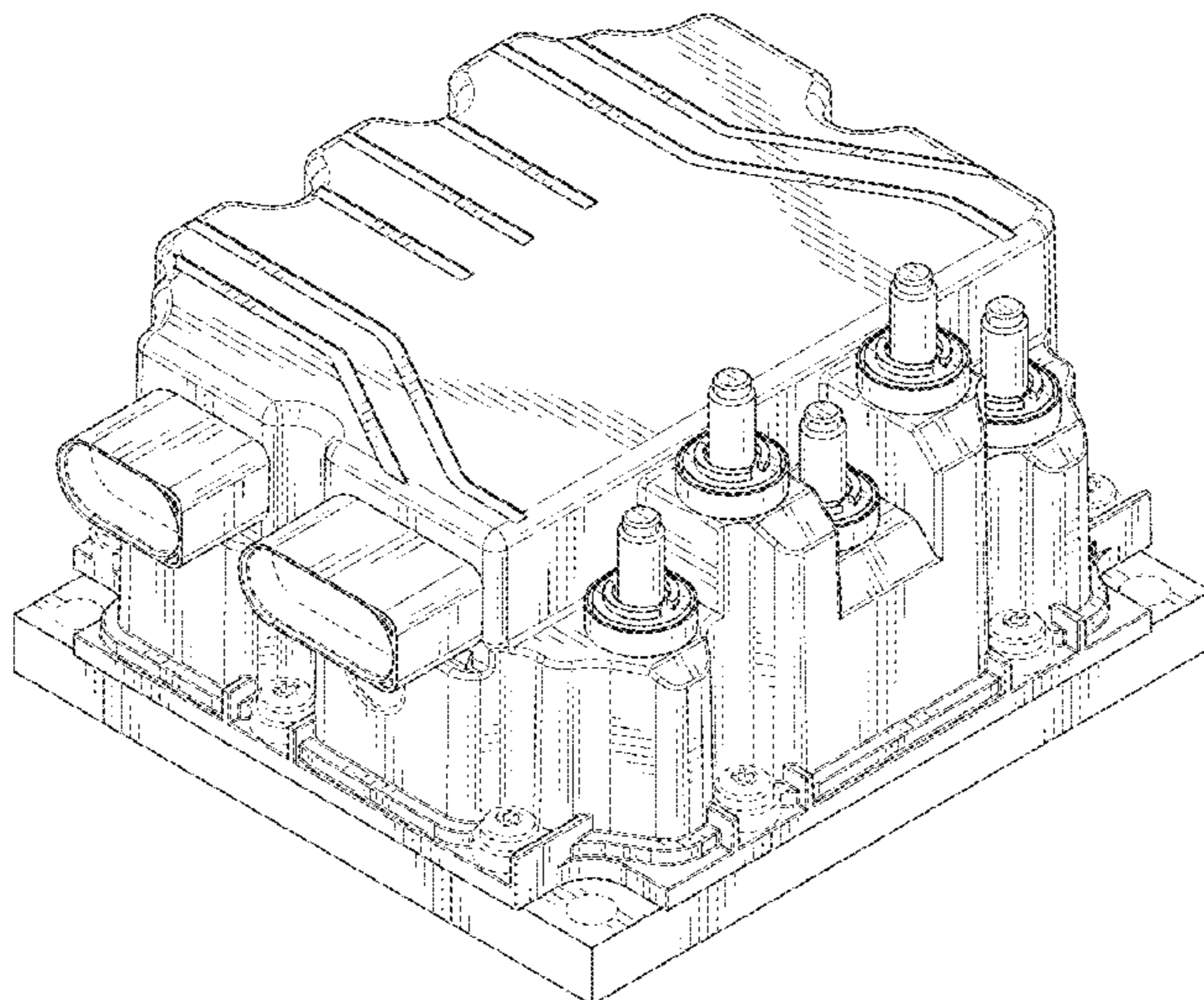
(57) **CLAIM**

The ornamental design for a module, as shown and described.

**DESCRIPTION**

FIG. 1 is a front top perspective view of a module.  
FIG. 2 is a top plan view thereof.  
FIG. 3 is a bottom plan view thereof.  
FIG. 4 is a front view thereof.  
FIG. 5 is a rear view thereof.  
FIG. 6 is a right side view thereof; and,  
FIG. 7 is a left side view thereof.  
The dash-dash broken lines depict portions of the module and form no part of the claimed design.

**1 Claim, 7 Drawing Sheets**



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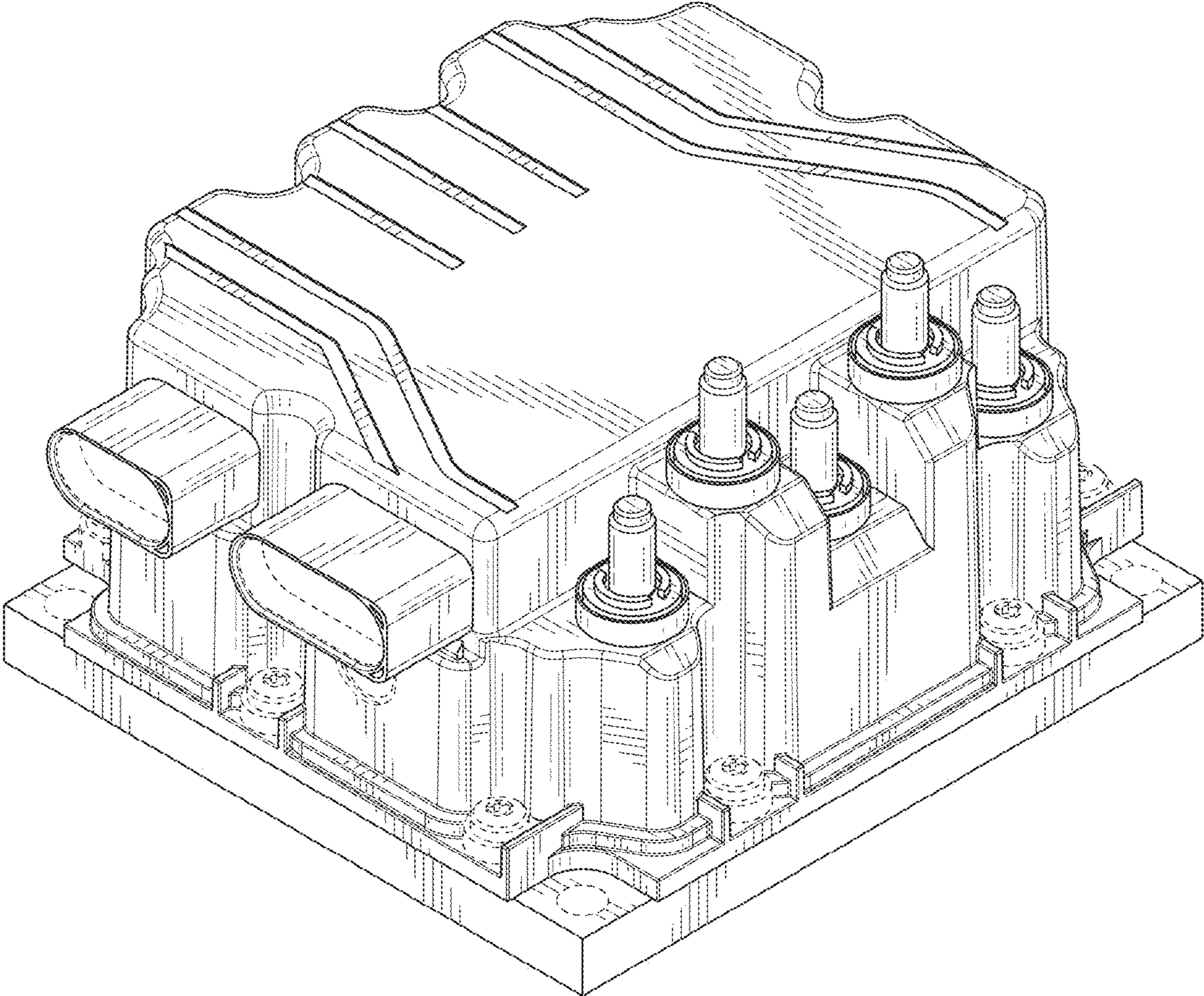


FIG. 1

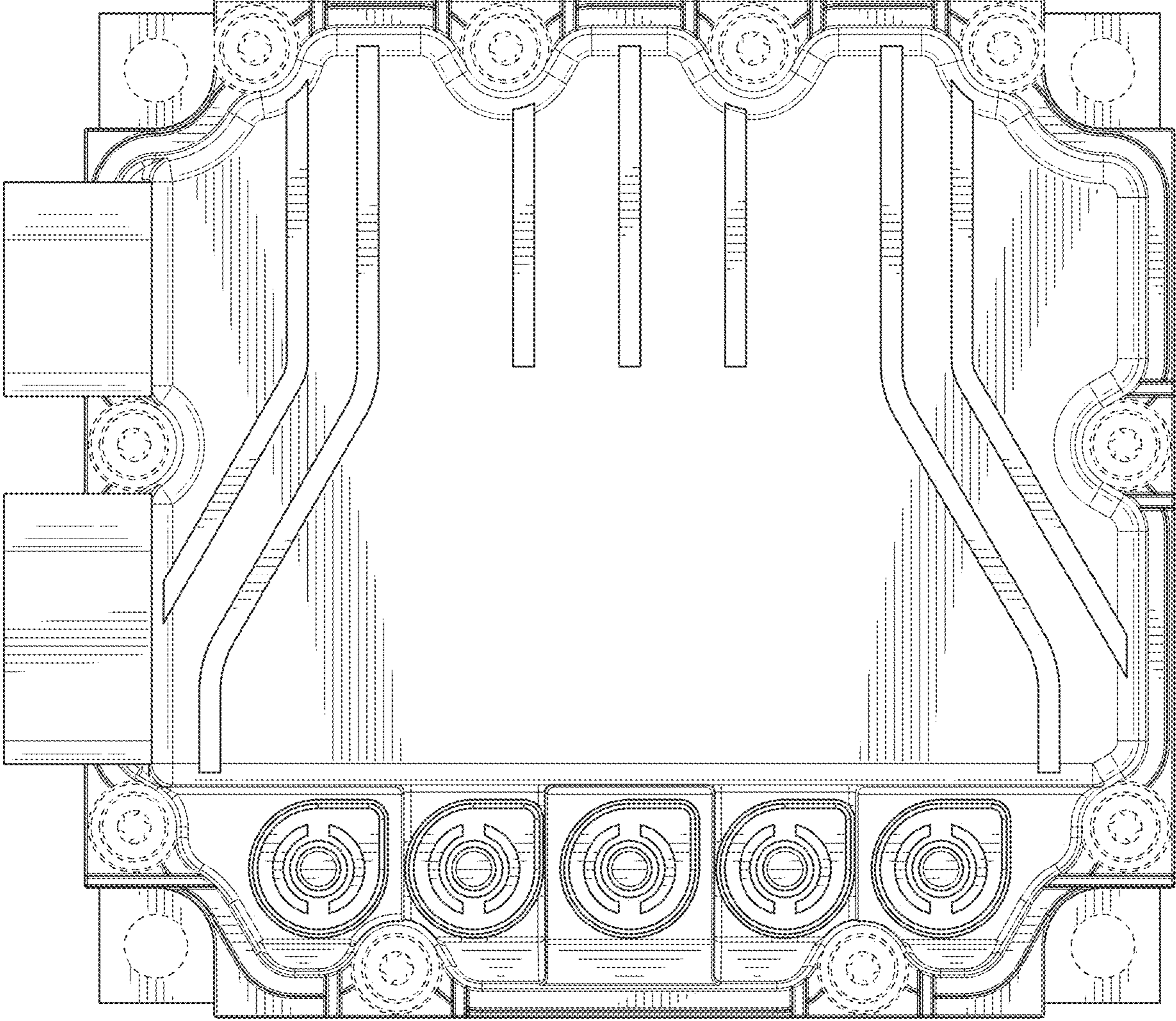


FIG. 2

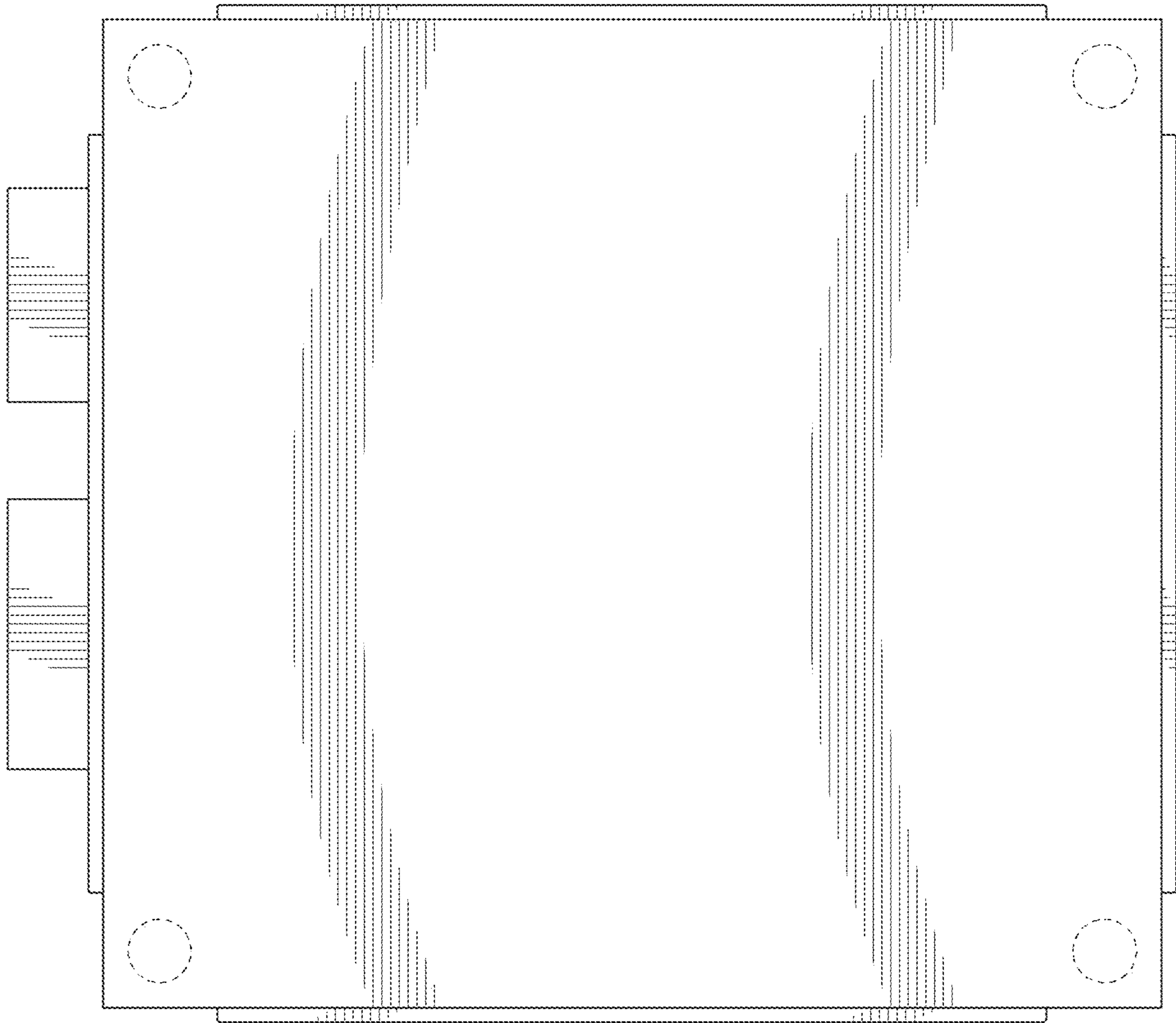


FIG. 3

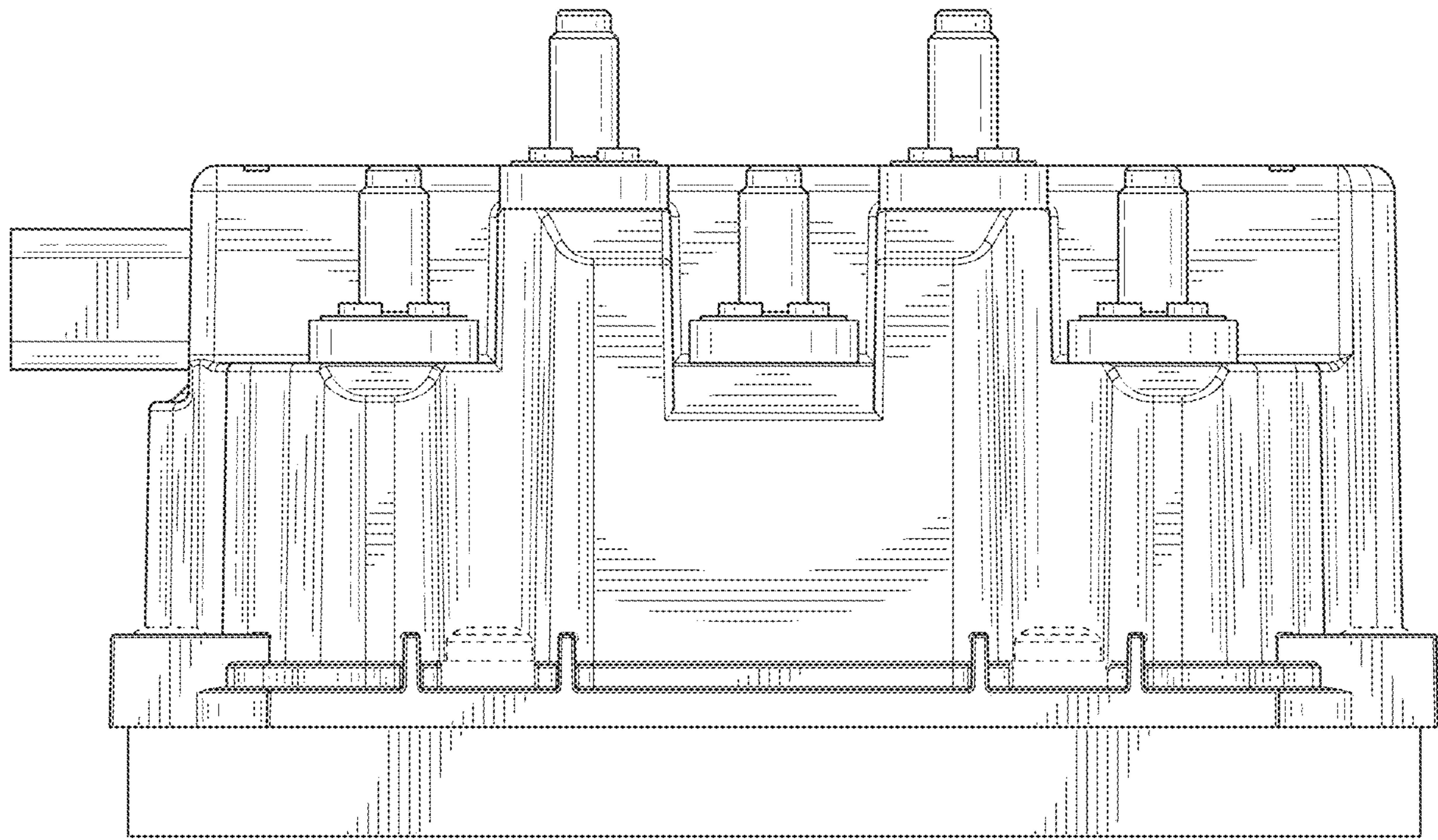


FIG. 4

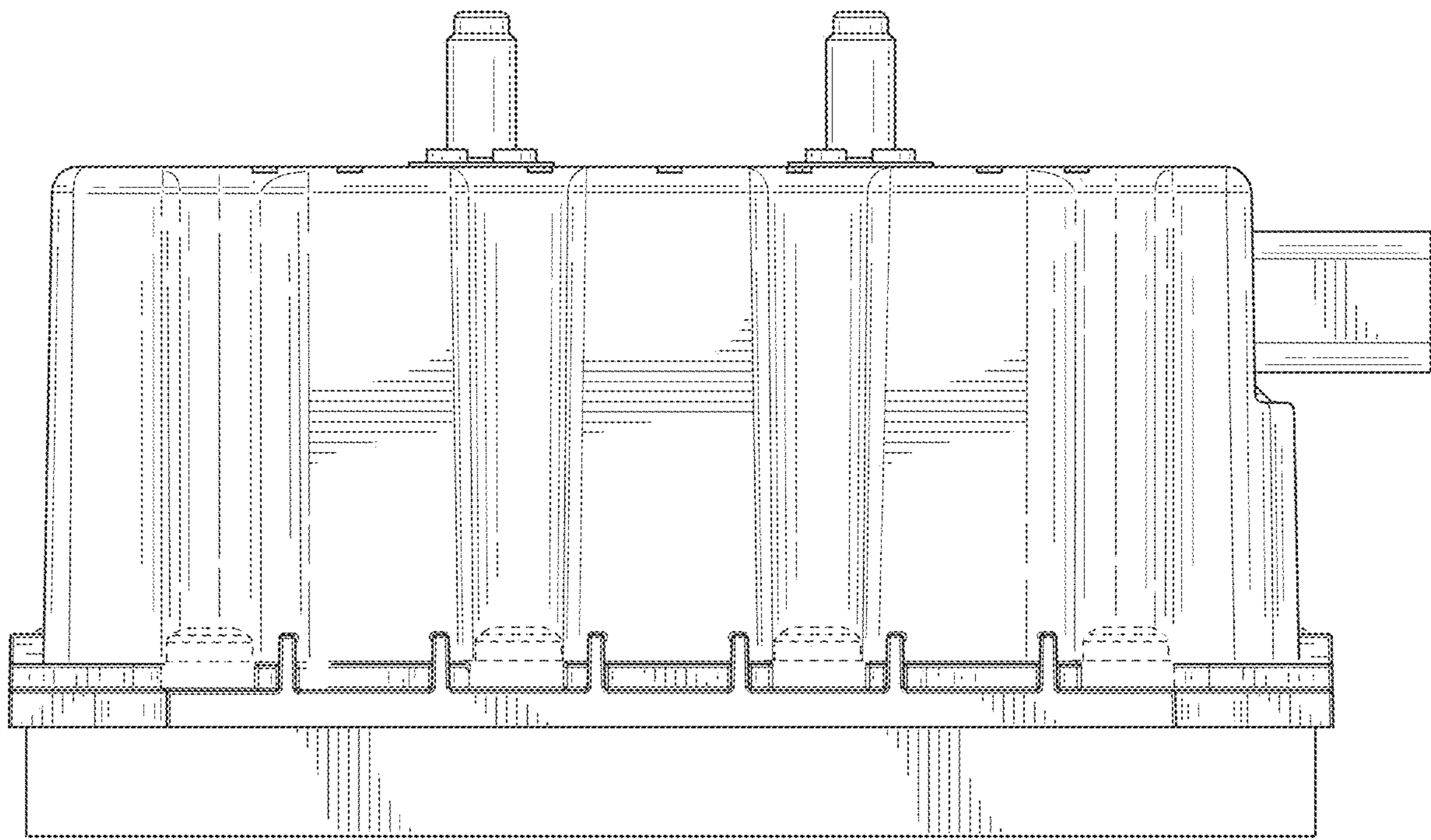


FIG. 5

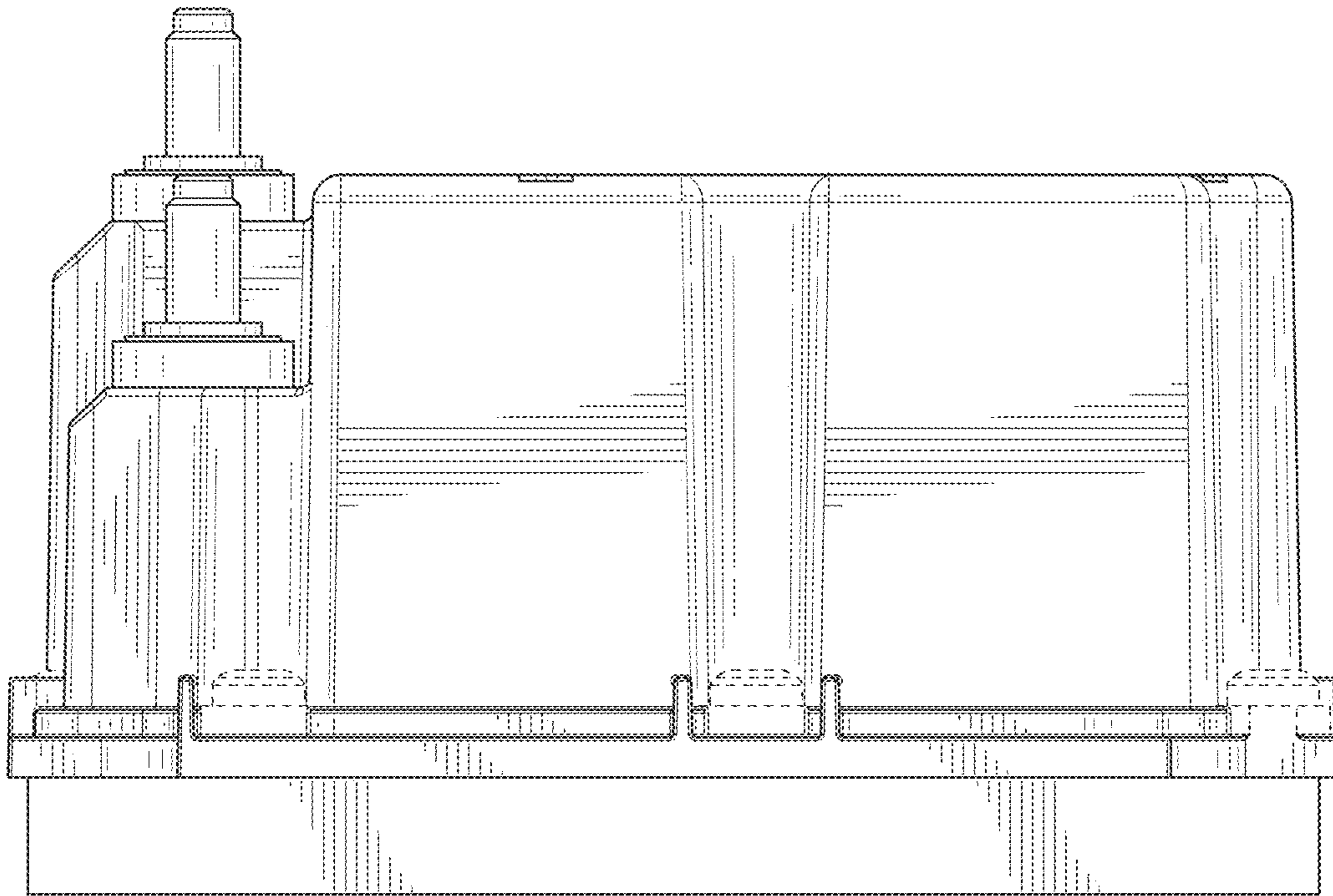


FIG. 6



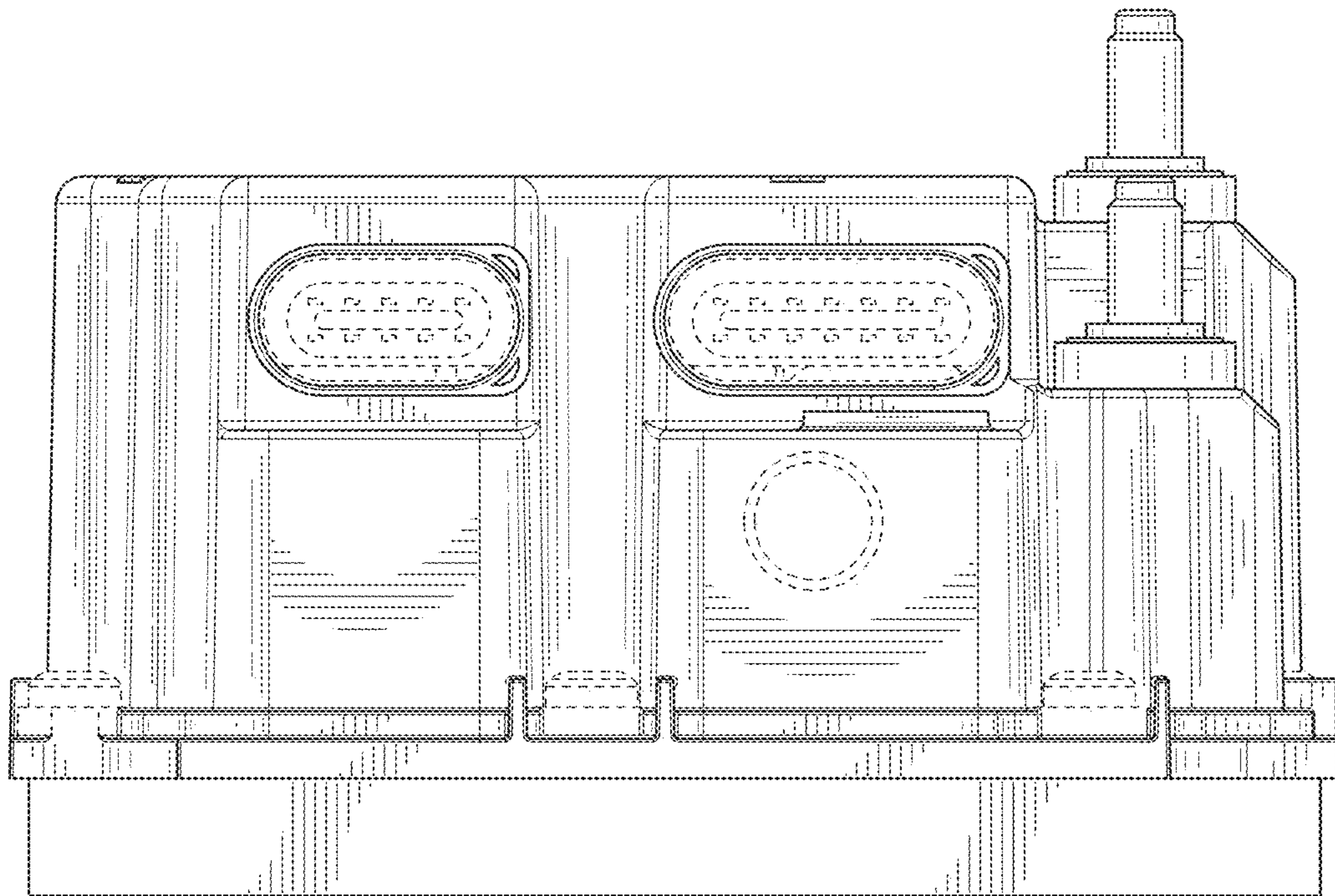


FIG. 7